

Product Change Notification

Change Title	DDR4 product change notice from Samsung 2400 1Gx8 B die IC to Samsung 2666 1Gx8 C die IC	Date	2021/12/17	PCN No	21121501
PCN level:	Major				
Models :	Innodisk DDR4 2400 Samsung 1Gx8 B die IC DRAM Module products				
Category:	Hardware - IC				

Key Characteristics of the Change:

Due to supply condition, Innodisk hereby to announce the product change plan for all of DDR4 2400 Samsung 1Gx8 B die IC assembled modules

Description:

Innodisk is going to process DDR4 2400 Samsung 1Gx8 B die IC product termination and running change to DDR4 2666 Samsung 1Gx8 C die IC product series. Include products below: DDR4 2400/2133 1Gx8 8GB & 16GB DRAM Modules

Key Milestone Dates

Last Purchase Date: 2022/03/31

Last Shipment Date: 2022/06/30

*Milestone dates are subject to change based on business and operational conditions.

Affected Model Table

#	Current Part Number	New Part Number
1	M4CS-8GS1L50J-B	M4CI-8GS1L5SJ-C
2	M4CS-8GS1L5RG-B	M4CI-8GS1L5RG-C
3	M4CS-8GS1LC0J-B	M4CI-8GS1LCSJ-C
4	M4CS-8GS1LCRG-B	M4CI-8GS1LCRG-C
5	M4CS-8GS1SC0J-B	M4CI-8GS1SCSJ-C
6	M4CS-8GS1SCRG-B	M4CI-8GS1SCRG-C
7	M4CS-AGS1M50J-B	M4CI-AGS1M5SJ-C
8	M4CS-AGS1M5RG-B	M4CI-AGS1M5RG-C
9	M4CS-AGS1MC0J-B	M4CI-AGS1MCSJ-C
10	M4CS-AGS1MCRG-B	M4CI-AGS1MCRG-C
11	M4CS-AGS1TC0J-B	M4CI-AGS1TCSJ-C
12	M4CS-AGS1TCRG-B	M4CI-AGS1TCRG-C
13	M4DS-8GS1IC0J-B	M4DI-8GS1ICSJ-C
14	M4DS-8GS1P50J-B	M4DI-8GS1P5SJ-C
15	M4DS-8GS1P5RG-B	M4DI-8GS1P5RG-C
16	M4DS-8GS1PC0J-B	M4DI-8GS1PCSJ-C
17	M4DS-8GS1PCRG-B	M4DI-8GS1PCRG-C
18	M4DS-AGS1Q50J-B	M4DI-AGS1Q5SJ-C
19	M4DS-AGS1Q5RG-B	M4DI-AGS1Q5RG-C
20	M4DS-AGS1QC0J-B	M4DI-AGS1QCSJ-C
21	M4DS-AGS1QCRG-B	M4DI-AGS1QCRG-C
22	M4GS-AGS1O5RG-B	M4GI-AGS1O5RG-C
23	M4MS-8GS15C0J-B	M4MI-8GS15CSJ-C
24	M4MS-8GS15C0J-B	M4MI-8GS15CCJ-C
25	M4MS-8GS1XC0J-B	M4MI-8GS1XCSJ-C
26	M4MS-AGS1YC0J-B	M4MI-AGS1YCSJ-C
27	M4PS-AGS1PC0J-B	M4PI-AGS1PCSJ-C
28	M4RS-8GS1A50J-B	M4RI-8GS1A5SJ-C
29	M4RS-8GS1A5RG-B	M4RI-8GS1A5RG-C
30	M4RS-8GS1AC0J-B	M4RI-8GS1ACSJ-C
31	M4RS-8GS1ACRG-B	M4RI-8GS1ACRG-C
32	M4RS-8GS1C50J-B	M4RI-8GS1C5SJ-C
33	M4RS-8GS1C5RG-B	M4RI-8GS1C5RG-C
34	M4RS-8GS1CC0J-B	M4RI-8GS1CCSJ-C
35	M4RS-8GS1CCRG-B	M4RI-8GS1CCRG-C
36	M4RS-AGS1B50J-B	M4RI-AGS1B5SJ-C
37	M4RS-AGS1B5RG-B	M4RI-AGS1B5RG-C
38	M4RS-AGS1BC0J-B	M4RI-AGS1BCSJ-C
39	M4RS-AGS1BCRG-B	M4RI-AGS1BCRG-C
40	M4RS-AGS1D50J-B	M4RI-AGS1D5SJ-C
41	M4RS-AGS1D5RG-B	M4RI-AGS1D5RG-C
42	M4RS-AGS1DC0J-B	M4RI-AGS1DCSJ-C
43	M4RS-AGS1DCRG-B	M4RI-AGS1DCRG-C
44	M4SS-8GS13C0J-B	M4SI-8GS13CSJ-C
45	M4SS-8GS13CRG-B	M4SI-8GS13CRG-C
46	M4SS-8GS1N50J-B	M4SI-8GS1N5SJ-C
47	M4SS-8GS1N5RG-B	M4SI-8GS1N5RG-C
48	M4SS-8GS1NC0J-B	M4SI-8GS1NCSJ-C
49	M4SS-8GS1NCRG-B	M4SI-8GS1NCRG-C
50	M4SS-8GS1NG0J-B	M4SI-8GS1NGSJ-C

51	M4SS-8GS1NGRG-B	M4SI-8GS1NGRG-C
52	M4SS-AGS1O10J-B	M4SI-AGS1O1SJ-C
53	M4SS-AGS1O50J-B	M4SI-AGS1O5SJ-C
54	M4SS-AGS1O5RG-B	M4SI-AGS1O5RG-C
55	M4SS-AGS1OC0J-B	M4SI-AGS1OCSJ-C
56	M4SS-AGS1OCRG-B	M4SI-AGS1OCRG-C
57	M4SS-AGS1OG0J-B	M4SI-AGS1OGSJ-C
58	M4SS-AGS1OGRG-B	M4SI-AGS1OGRG-C
59	M4US-8GS1J50J-B	M4UI-8GS1J5SJ-C
60	M4US-8GS1J5RG-B	M4UI-8GS1J5RG-C
61	M4US-8GS1JC0J-B	M4UI-8GS1JCSJ-C
62	M4US-8GS1JCRG-B	M4UI-8GS1JCRG-C
63	M4US-8GS1JG0J-B	M4UI-8GS1JGSJ-C
64	M4US-8GS1VC0J-B	M4UI-8GS1VCSJ-C
65	M4US-8GS1VCRG-B	M4UI-8GS1VCRG-C
66	M4US-AGS1K10J-B	M4UI-AGS1K1SJ-C
67	M4US-AGS1K50J-B	M4UI-AGS1K5SJ-C
68	M4US-AGS1K5RG-B	M4UI-AGS1K5RG-C
69	M4US-AGS1KC0J-B	M4UI-AGS1KCSJ-C
70	M4US-AGS1KCRG-B	M4UI-AGS1KCRG-C
71	M4US-AGS1KG0J-B	M4UI-AGS1KGSJ-C
72	M4US-AGS1KG0J-B	M4UI-AGS1KGSJ-C
73	M4US-AGS1KGRG-B	M4UI-AGS1KGRG-C
74	M4US-AGS1KGRG-B	M4UI-AGS1KGRG-C
75	M4US-AGS1W50J-B	M4UI-AGS1W5SJ-C
76	M4US-AGS1WC0J-B	M4UI-AGS1WCSJ-C
77	M4US-AGS1WCRG-B	M4UI-AGS1WCRG-C
78	M4US-AGS1WG0J-B	M4UI-AGS1WGSJ-C
79	M4XS-AGS1Q50J-B	M4XI-AGS1Q5SJ-C
80	M4XS-AGS1QC0J-B	M4XI-AGS1QCSJ-C

Notes:

Innodisk will reserve the right to process DDR4 product change all M4xS-xGS1xxxx-B to M4xI-xGS1xxxx-C and if the PN is not listed on above table.

(1) For the replacement samples, DDR4 2666 Samsung 1Gx8 C die IC assembled solutions are currently available.

(2) No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones. Innodisk apologizes for any inconvenience caused by this and appreciate your understanding.

(3) Innodisk promises that new items deliver quality and reliability are JEDEC compliant. If there is any further inquiry of our products or product specification, please contact your Innodisk contact sales person for support.

DRAM BU Vice President
Embedded DRAM Business Div.

Samson Chang